

Organisational Information

Sign up at: www.ecpe.org/events

Registration Deadline:

14 October 2026

Participation Fee:

Part 1 7-8 July	Part 2 21-22 Oct.	Both Tutorials	
770,- €*	670,- €*	1.250,- €*	Industry
655,- €*	520,- €*	955,- €*	University
240,- €*	180,- €*	380,- €*	Students/ PhD stud.**

* plus VAT; **students seats are limited

- The regular participation fee includes dinner, lunches, coffee/soft drinks. The reduced (PhD) students fee includes all the above except for dinner (can be booked for an extra fee of € 50,-*).
- The presentations will be provided by email via a download link shortly before the event. A printed version of the tutorial handout is available on request (€ 50,-*).
- Upon receipt of registration confirmation via email you are signed-up for the event. The invoice will be sent via email.
- 15 % discount for participants from ECPE member companies.
- 10 % discount for participants from ECPE competence centres.
- Further information (hotel list and maps) will be provided after registration and can be found on the ECPE web page.
- Cancellation policy: Full amount will be refunded in case of cancellation up to 2 weeks prior to the event. After this date and in case of no-show 50 % of the fee is non-refundable (substitutes are accepted anytime).
- The number of participants is limited to 35 attendees.
- We reserve the right to cancel the event or offer it as an online-only event if the minimum number of participants is not reached.

04/05/26

Organisational Information

Organiser ECPE e.V.
Ostendstrasse 181
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www.ecpe.org

Technical Chair Prof. Dr. Uwe Scheuermann,
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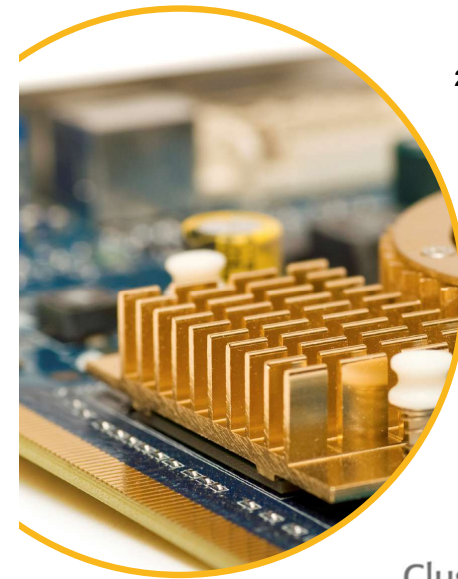


European Center for
Power Electronics e.V.

ECPE Tutorial

Thermal Engineering of Power Electronic Systems Part 2: Thermal Management and Reliability

21 - 22 October 2026
Erlangen, Germany



Cluster
Leistungselektronik

ECPE Tutorial

Thermal Engineering of Power Electronic Systems Part 2

21 - 22 October 2026
Erlangen, Germany

Thermal engineering of power electronic systems is a key to achieve high performance and reliability. With a clear focus on power modules the tutorial addresses the thermal design and validation of power electronic components exemplified by a 100 kW IGBT converter equipped with additional thermal sensors. The attendees should have basic knowledge on power semiconductor devices and power electronics systems.

Part 1: After a review of the basic theory of heat transfer, the calculation of losses in a voltage source inverter will be explained. For selected stationary operating conditions, the losses and device temperatures of the sample converter will be calculated from datasheet values, demonstrating the functionality of modern online tools provided by module manufacturers. Participants can choose between FEM simulations and equivalent thermal network calculation with LTspice™ to simulate device temperatures for defined losses, when system geometry and material layers are known. A 3rd practical training group will deal with the comparison of a simulated power board with measurement and calibrate afterwards the simulation model.

Part 2: Following a summary of the results of part 1, failure mechanisms, at both the semiconductor and package levels, will be introduced. After that, thermo-/damage-sensitive parameters will be discussed, along with the theoretical background of thermal impedance measurement. A practical demonstration of thermal impedance measurement with only standard laboratory equipment will conclude the first day. The second day will start with concrete design for reliability concepts, then aim straight at lifetime estimation, based on both power cycling and mission-profile approaches. Advanced electro-thermal and thermo-mechanical simulation will follow, and an overview of cooling systems and TIM materials will conclude the 2-day tutorial.

All presentations and discussions will be in English.

Programme

Wednesday, 21 October 2026

09:30 Start of Registration

09:45 Welcome
ECPE e.V.

10:00 Short Summary of the Results of
Tutorial Part1
Arendt Wintrich

10:20 Semiconductor-Level Thermal and Electrical
Failure Mechanisms
Francesco Iannuzzo

11:30 Temperature and Reliability: Package-Level
Failure Mechanisms I
Uwe Scheuermann

12:10 Lunch

13:10 Temperature and Reliability: Package-Level
Failure Mechanisms II
Uwe Scheuermann

14:10 Thermo-/Damage-Sensitive Electrical
Parameters
Francesco Iannuzzo

15:00 Thermal Impedance Measurement -
Preparation
Arendt Wintrich

15:15 Introduction to Experiment
Arendt Wintrich

15:30 Coffee Break

16:00 Thermal Impedance Measurement – Results
and Interpretation
Arendt Wintrich

16:15 Extraction and Application of Thermal
Networks
Martin Pfof

17:30 Wrap up 1st Day

18:00 End of 1st Day

19:00 Dinner

Programme

Thursday, 22 October 2026

08:30 Start of 2nd Day

08:30 Design for Reliability
Uwe Scheuermann

09:30 Lifetime Models based on Power Cycling Test
Uwe Scheuermann

10:00 Coffee Break

10:20 Mission Profile based Lifetime Estimation
Francesco Iannuzzo

11:15 Electro-Thermal and Thermo-Mechanical
Simulation
Martin Pfof

12:30 Lunch

13:30 Thermal Simulation of Complex Power
Packages Considering Reliability Issues
Andreas Simon-Kajda

14:30 Special Effects and Alternative Cooling
Technologies
Arendt Wintrich

15:15 TIM Materials
Arendt Wintrich

15:45 Wrap up 2nd Day, Final Discussion, Feedback

16:00 End of Tutorial

Course instructors:

- Prof. Francesco Iannuzzo, Polytechnic of Turin
- Prof. Martin Pfof, TU Dortmund University
- Prof. Uwe Scheuermann, Friedrich-Alexander-Universität Erlangen-Nürnberg
- Andreas Simon-Kajda, Siemens Industry Software
- Dr. Arendt Wintrich, Semikron Danfoss